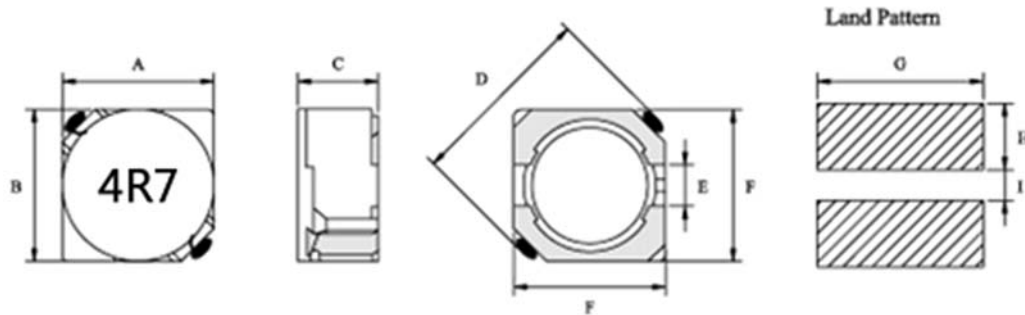


## FEATRLRES

- Magnetic Shielded surface mount inductor with high current rating.
- Low resistance to keep power loss minimum.
- 100% Lead(Pb) & Halogen-Free and RoHS compliant.

## CONFIGLRATIONS & DIMENSIONS ( unit in mm )



Type	A±0.3	B±0.3	C(max)	D(max)	E(Ref.)	F(Ref.)	G	H	I
HRH5D28	5.7	5.7	3.0	8.2	2.0	5.5	6.3	2.15	2.0

## ELECTRICAL CHARACTERISTICS

Part Number	Inductance (uH)	Tolerance (%)	Test Frequency (Hz)	DCR (Ω) max.	IDC (A) max.
HRH5D28-2R6Y	2.6	± 30%	0.1V/10K	0.018	2.60
HRH5D28-3R0Y	3.0	± 30%	0.1V/10K	0.024	2.40
HRH5D28-4R2Y	4.2	± 30%	0.1V/10K	0.031	2.20
HRH5D28-5R3Y	5.3	± 30%	0.1V/10K	0.038	1.90
HRH5D28-6R2Y	6.2	± 30%	0.1V/10K	0.045	1.80
HRH5D28-8R2Y	8.2	± 30%	0.1V/10K	0.053	1.60
HRH5D28-100Y	10	± 30%	0.1V/10K	0.065	1.30
HRH5D28-120Y	12	± 30%	0.1V/10K	0.076	1.20
HRH5D28-150Y	15	± 30%	0.1V/10K	0.103	1.10
HRH5D28-180Y	18	± 30%	0.1V/10K	0.110	1.00
HRH5D28-220Y	22	± 30%	0.1V/10K	0.122	0.90
HRH5D28-270Y	27	± 30%	0.1V/10K	0.175	0.85
HRH5D28-330Y	33	± 30%	0.1V/10K	0.189	0.75
HRH5D28-390Y	39	± 30%	0.1V/10K	0.212	0.70
HRH5D28-470Y	47	± 30%	0.1V/10K	0.260	0.62
HRH5D28-560Y	56	± 30%	0.1V/10K	0.305	0.58

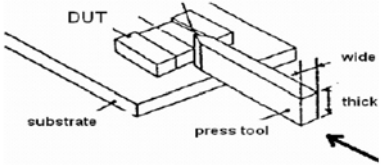
HRH5D28-680Y	68	± 30%	0.1V/10K	0.355	0.52
HRH5D28-820Y	82	± 30%	0.1V/10K	0.463	0.46
HRH5D28-101Y	100	± 30%	0.1V/10K	0.520	0.42

Note:

Based on inductance change ( $\Delta L/L0 : \leq -35\%$ ) @ ambient temp. 25°C Based on temperature rise ( $\Delta T : 40^\circ\text{C typ.}$ )

## Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125°C (Including self - temperature rise)	
Storage temperature	1. -10~+40°C, 50~60%RH (Product with taping) 2. -40~+125°C (on board)	
<b>Electrical Performance Test</b>		
Inductance	Refer to standard electrical characteristics list.	HP4284A, CH11025, CH3302, CH1320, CH1320S LCR Meter.
DCR		CH16502, Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately $\Delta L30\%$	Saturation DC Current (Isat) will cause L0 to drop $\Delta L(\%)$
Heat Rated Current (Irms)	Approximately $\Delta T40^\circ\text{C}$	Heat Rated Current (Irms) will cause the coil temperature rise $\Delta T(^\circ\text{C})$ . 1. Applied the allowed DC current 2. Temperature measured by digital surface thermometer
<b>Reliability Test</b>		
Life Test	Appearance : No damage. Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Temperature : $125 \pm 2^\circ\text{C}$ (Inductor) Applied current : rated current Duration : 1000 $\pm$ 12hrs Measured at room temperature after placing for 24 $\pm$ 2 hrs
Load Humidity		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Humidity : $85 \pm 2 \times \text{R.H.}$ , Temperature : $85^\circ\text{C} \pm 2^\circ\text{C}$ Duration : 1000hrs Min. with 100% rated current Measured at room temperature after placing for 24 $\pm$ 2 hrs
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020D Classification Reflow Profiles) 1. Baked at $50^\circ\text{C}$ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25^\circ\text{C}$ in 2.5hrs. 3. Raise temperature to $65 \pm 2^\circ\text{C}$ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to $25^\circ\text{C}$ in 2.5hrs, keep at $25^\circ\text{C}$ for 2 hrs then keep at $-10^\circ\text{C}$ for 3 hrs 4. Keep at $25^\circ\text{C}$ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020D Classification Reflow Profiles) Condition for 1 cycle Step1 : $-40 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Step2 : $25 \pm 2^\circ\text{C}$ $\leq 0.5$ min Step3 : $125 \pm 2^\circ\text{C}$ 30 $\pm$ 5min Number of cycles : 500 Measured at room temperature after placing for 24 $\pm$ 2 hrs
Vibration		Oscillation Frequency: 10 ~ 2K ~ 10Hz for 20 minutes Equipment : Vibration checker Total Amplitude: 1.52mm $\pm$ 10% Testing Time : 12 hours (20 minutes, 12 cycles each of 3 orientations).

Bending		Shall be mounted on a FR4 substrate of the following dimensions: $\geq 0.805$ inch(2012mm):40x100x1.2mm $< 0.805$ inch(2012mm):40x100x0.8mm Bending depth: $\geq 0.805$ inch(2012mm):1.2mm $< 0.805$ inch(2012mm):0.8mm duration of 10 sec.															
Shock	Appearance : No damage. Impedance : within $\pm 15\%$ of initial value Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value	<table border="1"> <thead> <tr> <th>Type</th> <th>Peak value (g's)</th> <th>Normal duration (D) (ms)</th> <th>Wave form</th> <th>Velocity change (Vi)ft/sec</th> </tr> </thead> <tbody> <tr> <td>SMD</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> <tr> <td>Lead</td> <td>50</td> <td>11</td> <td>Half-sine</td> <td>11.3</td> </tr> </tbody> </table>	Type	Peak value (g's)	Normal duration (D) (ms)	Wave form	Velocity change (Vi)ft/sec	SMD	50	11	Half-sine	11.3	Lead	50	11	Half-sine	11.3
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Lead	50	11	Half-sine	11.3													
Solder ability	More than 95% of the terminal electrode should be covered with solder.	Preheat: 150°C,60sec.. Solder: Sn96.5% Ag3% Cu0.5% Temperature: 245 $\pm$ 5°C ◦ Flux for lead free: Rosin. 9.5% ◦ Dip time: 4 $\pm$ 1sec ◦ Depth: completely cover the termination															
Resistance to Soldering Heat		Depth: completely cover the termination <table border="1"> <thead> <tr> <th>Temperature(°C)</th> <th>Time(s)</th> <th>Temperature ramp/immersion and emersion rate</th> <th>Number of heat cycles</th> </tr> </thead> <tbody> <tr> <td>260 <math>\pm</math>5 (solder temp)</td> <td>10 <math>\pm</math>1</td> <td>25mm/s <math>\pm</math>6 mm/s</td> <td>1</td> </tr> </tbody> </table>	Temperature(°C)	Time(s)	Temperature ramp/immersion and emersion rate	Number of heat cycles	260 $\pm$ 5 (solder temp)	10 $\pm$ 1	25mm/s $\pm$ 6 mm/s	1							
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Terminal Strength	Appearance : No damage. Impedance : within $\pm 15\%$ of initial value Inductance : within $\pm 10\%$ of initial value Q : Shall not exceed the specification value. RDC : within $\pm 15\%$ of initial value and shall not exceed the specification value e	Preconditioning: Run through IR reflow for 2 times.( IPC/JEDEC J-STD-020DClassification Reflow Profiles With the component mounted on a PCB with the device to be tested, apply a force( $>0.805:1$ kg , $\leq 0.805:0.5$ kg)to the side of a device being tested. This force shall be applied for 60 $\pm$ 1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested. 															

Note : When there are questions concerning measurement result : measurement shall be made after 48  $\pm$  2 hours of recovery under the standard condition.